

INFORMATION
DISCLOSURE
CITATION

Applicant: Takemi MUROGA et al

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U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No.	Document Number - Kind Code	Publication Date MM-DD-YYYY	Name of Patentee or Applicant
CL	AA	2002/0076567 A1	06-20-2002	HONJO et al
	AB			
	AC			

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No.	Country Code - Document Number - Kind Code	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Trans.
CL	AD	EP 1 195 819 A1	04-10-2002	BELOUET	
CL	AE	WO 03/044836 A2	05-30-2003	HOLESENGER et al	
	AF				
	AG				

NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.	(Include Author, Title, Date, Pages, Etc.)
CL	AH	Deposition of CeO ₂ /YSZ buffer layer on Hastelloy substrates for MOD process of YBa ₂ Cu ₃ O _{7-x} film, by Hiroshi Fuji et al, Physica C, vol. 357-360, August 2001, pages 1101-1014
	AI	In-plane aligned YBa ₂ Cu ₃ O _{7-x} thin films deposited on polycrystalline metallic substrates, by Y. Iijima et al, Applied Physics Letters, vol. 60, no. 6, February 1992, pages 769-771
	AJ	The effect of a MgO seed layer on the biepitaxial growth of Y ₁ Ba ₂ Cu ₃ O _{7-x} overlayers in various multilayered thin films, by SangSuk Lee et al, Thin Solid Films, vol. 258, no. 1/2, March 1995, pages 299-304
	AK	Growth and characterization of superconducting films TI _{0.78} Bi _{0.22} SR _{1.6} Ba _{0.4} Ca ₂ Cu ₃ O ₇ on CeO ₂ -buffered single crystal YSZ, by Z.F. Ren et al, Physica C, vol. 306, no. 1-2, September 1998, pages 149-153
CL	AL	Fabrication of YBa ₂ Cu ₃ O _{7-x} Films of Buffered Metal Tapes Fired at Low Temperature by MOD Method using Trifluoroacetate Salts, by T. Araki et al, IEEE Transactions on Applied Superconductivity, vol. 11, no. 1, March 2001, pages 2869-2872
EXAMINER SIGNATURE		DATE CONSIDERED
Gordon P. Cooke		2/10/06

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.